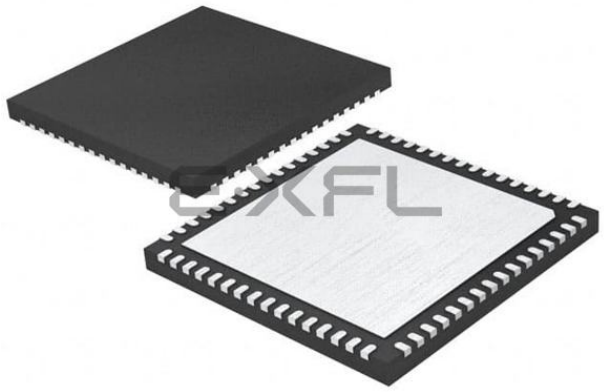
Microchip Technology - PIC32MX420F032HT-40I/MR Datasheet



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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	MIPS32® M4K™
Core Size	32-Bit Single-Core
Speed	40MHz
Connectivity	I²C, IrDA, LINbus, PMP, SPI, UART/USART, USB OTG
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	53
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 3.6V
Data Converters	A/D 16x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-VFQFN Exposed Pad
Supplier Device Package	64-VQFN (9x9)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic32mx420f032ht-40i-mr

TABLE 1-1: PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number[1]			Pin Type	Buffer Type	Description
	64-pin QFN/TQFP	100-pin TQFP	121-pin XBGA			
RG0	—	90	A5	I/O	ST	PORTG is a bidirectional I/O port.
RG1	—	89	E6	I/O	ST	
RG6	4	10	E3	I/O	ST	
RG7	5	11	F4	I/O	ST	
RG8	6	12	F2	I/O	ST	
RG9	8	14	F3	I/O	ST	
RG12	—	96	C3	I/O	ST	
RG13	—	97	A3	I/O	ST	
RG14	—	95	C4	I/O	ST	
RG15	—	1	B2	I/O	ST	
RG2	37	57	H10	I	ST	PORTG input pins.
RG3	36	56	J11	I	ST	
T1CK	48	74	B11	I	ST	Timer1 external clock input.
T2CK	—	6	D1	I	ST	Timer2 external clock input.
T3CK	—	7	E4	I	ST	Timer3 external clock input.
T4CK	—	8	E2	I	ST	Timer4 external clock input.
T5CK	—	9	E1	I	ST	Timer5 external clock input.
$\overline{U1CTS}$	43	47	L9	I	ST	UART1 clear to send.
$\overline{U1RTS}$	35, 49	48	K9	O	—	UART1 ready to send.
U1RX	34, 50	52	K11	I	ST	UART1 receive.
U1TX	33, 51	51, 53	J10, K10	O	—	UART1 transmit.
$\overline{U2CTS}$	21	40	K6	I	ST	UART2 clear to send.
$\overline{U2RTS}$	29	39	L6	O	—	UART2 ready to send.
U2RX	31	49	L10	I	ST	UART2 receive.
U2TX	32	50	L11	O	—	UART2 transmit.
SCK1	35	55, 70	D11, H9	I/O	ST	Synchronous serial clock input/output for SPI1.
SDI1	34	9, 54	E1, H8	I	ST	SPI1 data in.
SDO1	33	53, 72	D9, J10	O	—	SPI1 data out.
$\overline{SS1}$	14	23, 69	E10, J2	I/O	ST	SPI1 slave synchronization or frame pulse I/O.
SCK2	4	10	E3	I/O	ST	Synchronous serial clock input/output for SPI2.
SDI2	5	11	F4	I	ST	SPI2 data in.
SDO2	6	12	F2	O	—	SPI2 data out.
$\overline{SS2}$	8	14	F3	I/O	ST	SPI2 slave synchronization or frame pulse I/O.
SCL1	37, 44	57, 66	E11, H10	I/O	ST	Synchronous serial clock input/output for I2C1.
SDA1	36, 43	56, 67	E8, J11	I/O	ST	Synchronous serial data input/output for I2C1.
SCL2	32	58	H11	I/O	ST	Synchronous serial clock input/output for I2C2.
SDA2	31	59	G10	I/O	ST	Synchronous serial data input/output for I2C2.

Legend: CMOS = CMOS compatible input or output; Analog = Analog input; P = Power
ST = Schmitt Trigger input with CMOS levels; O = Output; I = Input
TTL = TTL input buffer

Note 1: Pin numbers are provided for reference only. See the **"Pin Diagrams"** section for device pin availability.

TABLE 1-1: PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number(1)			Pin Type	Buffer Type	Description
	64-pin QFN/TQFP	100-pin TQFP	121-pin XBGA			
PMD0	60	93	A4	I/O	TTL/ST	Parallel Master Port Data (De-multiplexed Master mode) or Address/Data (Multiplexed Master modes).
PMD1	61	94	B4	I/O	TTL/ST	
PMD2	62	98	B3	I/O	TTL/ST	
PMD3	63	99	A2	I/O	TTL/ST	
PMD4	64	100	A1	I/O	TTL/ST	
PMD5	1	3	D3	I/O	TTL/ST	
PMD6	2	4	C1	I/O	TTL/ST	
PMD7	3	5	D2	I/O	TTL/ST	
PMD8	—	90	A5	I/O	TTL/ST	
PMD9	—	89	E6	I/O	TTL/ST	
PMD10	—	88	A6	I/O	TTL/ST	
PMD11	—	87	B6	I/O	TTL/ST	
PMD12	—	79	A9	I/O	TTL/ST	
PMD13	—	80	D8	I/O	TTL/ST	
PMD14	—	83	D7	I/O	TTL/ST	
PMD15	—	84	C7	I/O	TTL/ST	
PMRD	53	82	B8	O	—	Parallel Master Port Read Strobe.
PMWR	52	81	C8	O	—	Parallel Master Port Write Strobe.
PMALL	30	44	L8	O	—	Parallel Master Port Address Latch Enable low-byte (Multiplexed Master modes).
PMALH	29	43	K7	O	—	Parallel Master Port Address Latch Enable high-byte (Multiplexed Master modes).
VBUS	34	54	H8	I	Analog	USB Bus Power Monitor.
VUSB	35	55	H9	P	—	USB Internal Transceiver Supply. If the USB module is *not* used, this pin must be connected to VDD.
VBUSON	11	20	H1	O	—	USB Host and OTG Bus Power Control Output.
D+	37	57	H10	I/O	Analog	USB D+.
D-	36	56	J11	I/O	Analog	USB D-.
USBID	33	51	K10	I	ST	USB OTG ID Detect.
ENVREG	57	86	A7	I	ST	Enable for On-Chip Voltage Regulator.
TRCLK	—	91	C5	O	—	Trace Clock.
TRD0	—	97	A3	O	—	Trace Data Bits 0-3.
TRD1	—	96	C3	O	—	
TRD2	—	95	C4	O	—	
TRD3	—	92	B5	O	—	
PGED1	16	25	K2	I/O	ST	Data I/O pin for programming/debugging communication channel 1.
PGEC1	15	24	K1	I	ST	Clock input pin for programming/debugging communication channel 1.

Legend: CMOS = CMOS compatible input or output; Analog = Analog input; P = Power
ST = Schmitt Trigger input with CMOS levels; O = Output; I = Input
TTL = TTL input buffer

Note 1: Pin numbers are provided for reference only. See the **"Pin Diagrams"** section for device pin availability.

2.11 Referenced Sources

This device data sheet is based on the following individual chapters of the *"PIC32 Family Reference Manual"*. These documents should be considered as the general reference for the operation of a particular module or device feature.

Note 1: To access the documents listed below, browse to the documentation section of the PIC32MX460F512L product page on the Microchip web site (www.microchip.com) or select a family reference manual section from the following list.

In addition to parameters, features, and other documentation, the resulting page provides links to the related family reference manual sections.

- **Section 1. "Introduction"** (DS61127)
- **Section 2. "CPU"** (DS61113)
- **Section 3. "Memory Organization"** (DS61115)
- **Section 4. "Prefetch Cache"** (DS61119)
- **Section 5. "Flash Program Memory"** (DS61121)
- **Section 6. "Oscillator Configuration"** (DS61112)
- **Section 7. "Resets"** (DS61118)
- **Section 8. "Interrupt Controller"** (DS61108)
- **Section 9. "Watchdog Timer and Power-up Timer"** (DS61114)
- **Section 10. "Power-Saving Features"** (DS61130)
- **Section 12. "I/O Ports"** (DS61120)
- **Section 13. "Parallel Master Port (PMP)"** (DS61128)
- **Section 14. "Timers"** (DS61105)
- **Section 15. "Input Capture"** (DS61122)
- **Section 16. "Output Compare"** (DS61111)
- **Section 17. "10-bit Analog-to-Digital Converter (ADC)"** (DS61104)
- **Section 19. "Comparator"** (DS61110)
- **Section 20. "Comparator Voltage Reference (CV$_{REF}$)"** (DS61109)
- **Section 21. "Universal Asynchronous Receiver Transmitter (UART)"** (DS61107)
- **Section 23. "Serial Peripheral Interface (SPI)"** (DS61106)
- **Section 24. "Inter-Integrated Circuit™ (I^{2}C™)"** (DS61116)
- **Section 27. "USB On-The-Go (OTG)"** (DS61126)
- **Section 29. "Real-Time Clock and Calendar (RTCC)"** (DS61125)
- **Section 31. "Direct Memory Access (DMA) Controller"** (DS61117)
- **Section 32. "Configuration"** (DS61124)
- **Section 33. "Programming and Diagnostics"** (DS61129)

4.0 MEMORY ORGANIZATION

Note 1: This data sheet summarizes the features of the PIC32MX3XX/4XX family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 3. "Memory Organization"** (DS61115) of the *"PIC32 Family Reference Manual",* which is available from the Microchip web site (www.microchip.com/PIC32).

PIC32MX3XX/4XX microcontrollers provide 4 GB of unified virtual memory address space. All memory regions including program, data memory, SFRs and Configuration registers reside in this address space at their respective unique addresses. The program and data memories can be optionally partitioned into user and kernel memories. In addition, the data memory can be made executable, allowing PIC32MX3XX/4XX to execute from data memory.

4.1 Key Features

- 32-bit native data width
- Separate User and Kernel mode address space
- Flexible program Flash memory partitioning
- Flexible data RAM partitioning for data and program space
- Separate boot Flash memory for protected code
- Robust bus exception handling to intercept runaway code
- Simple memory mapping with Fixed Mapping Translation (FMT) unit
- Cacheable and non-cacheable address regions

4.2 PIC32MX3XX/4XX Memory Layout

PIC32MX3XX/4XX microcontrollers implement two address spaces: Virtual and Physical. All hardware resources such as program memory, data memory and peripherals are located at their respective physical addresses. Virtual addresses are exclusively used by the CPU to fetch and execute instructions as well as access peripherals. Physical addresses are used by peripherals such as DMA and Flash controller that access memory independently of CPU.

TABLE 4-5: INTERRUPT REGISTERS MAP FOR PIC32MX440F128H, PIC32MX440F256H AND PIC32MX440F512H DEVICES ONLY(1)

Virtual Address (BF88_#)	Register Name	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
1000	INTCON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	SS0	0000
		15:0	—	—	—	MVEC	—	TPC<2:0>			—	—	—	INT4EP	INT3EP	INT2EP	INT1EP	INT0EP	0000
1010	INTSTAT(2)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	SRIPL<2:0>			—	—	VEC<5:0>						0000
1020	IPTMR	31:16	IPTMR<31:0>																0000
		15:0																	0000
1030	IFS0	31:16	I2C1MIF	I2C1SIF	I2C1BIF	U1TXIF	U1RXIF	U1EIF	—	—	—	OC5IF	IC5IF	T5IF	INT4IF	OC4IF	IC4IF	T4IF	0000
		15:0	INT3IF	OC3IF	IC3IF	T3IF	INT2IF	OC2IF	IC2IF	T2IF	INT1IF	OC1IF	IC1IF	T1IF	INT0IF	CS1IF	CS0IF	CTIF	0000
1040	IFS1	31:16	—	—	—	—	—	—	USBIF	FCEIF	—	—	—	—	DMA3IF	DMA2IF	DMA1IF	DMA0IF	0000
		15:0	RTCCIF	FSCMIF	I2C2MIF	I2C2SIF	I2C2BIF	U2TXIF	U2RXIF	U2EIF	SPI2RXIF	SPI2TXIF	SPI2EIF	CMP2IF	CMP1IF	PMPIF	AD1IF	CNIF	0000
1060	IEC0	31:16	I2C1MIE	I2C1SIE	I2C1BIE	U1TXIE	U1RXIE	U1EIE	—	—	—	OC5IE	IC5IE	T5IE	INT4IE	OC4IE	IC4IE	T4IE	0000
		15:0	INT3IE	OC3IE	IC3IE	T3IE	INT2IE	OC2IE	IC2IE	T2IE	INT1IE	OC1IE	IC1IE	T1IE	INT0IE	CS1IE	CS0IE	CTIE	0000
1070	IEC1	31:16	—	—	—	—	—	—	USBIE	FCEIE	—	—	—	—	DMA3IE	DMA2IE	DMA1IE	DMA0IE	0000
		15:0	RTCCIE	FSCMIE	I2C2MIE	I2C2SIE	I2C2BIE	U2TXIE	U2RXIE	U2EIE	SPI2RXIE	SPI2TXIE	SPI2EIE	CMP2IE	CMP1IE	PMPIE	AD1IE	CNIE	0000
1090	IPC0	31:16	—	—	—	INT0IP<2:0>			INT0IS<1:0>		—	—	—	CS1IP<2:0>			CS1IS<1:0>		0000
		15:0	—	—	—	CS0IP<2:0>			CS0IS<1:0>		—	—	—	CTIP<2:0>			CTIS<1:0>		0000
10A0	IPC1	31:16	—	—	—	INT1IP<2:0>			INT1IS<1:0>		—	—	—	OC1IP<2:0>			OC1IS<1:0>		0000
		15:0	—	—	—	IC1IP<2:0>			IC1IS<1:0>		—	—	—	T1IP<2:0>			T1IS<1:0>		0000
10B0	IPC2	31:16	—	—	—	INT2IP<2:0>			INT2IS<1:0>		—	—	—	OC2IP<2:0>			OC2IS<1:0>		0000
		15:0	—	—	—	IC2IP<2:0>			IC2IS<1:0>		—	—	—	T2IP<2:0>			T2IS<1:0>		0000
10C0	IPC3	31:16	—	—	—	INT3IP<2:0>			INT3IS<1:0>		—	—	—	OC3IP<2:0>			OC3IS<1:0>		0000
		15:0	—	—	—	IC3IP<2:0>			IC3IS<1:0>		—	—	—	T3IP<2:0>			T3IS<1:0>		0000
10D0	IPC4	31:16	—	—	—	INT4IP<2:0>			INT4IS<1:0>		—	—	—	OC4IP<2:0>			OC4IS<1:0>		0000
		15:0	—	—	—	IC4IP<2:0>			IC4IS<1:0>		—	—	—	T4IP<2:0>			T4IS<1:0>		0000
10E0	IPC5	31:16	—	—	—	—	—	—	—	—	—	—	—	OC5IP<2:0>			OC5IS<1:0>		0000
		15:0	—	—	—	IC5IP<2:0>			IC5IS<1:0>		—	—	—	T5IP<2:0>			T5IS<1:0>		0000
10F0	IPC6	31:16	—	—	—	AD1IP<2:0>			AD1IS<1:0>		—	—	—	CNIP<2:0>			CNIS<1:0>		0000
		15:0	—	—	—	I2C1IP<2:0>			I2C1IS<1:0>		—	—	—	U1IP<2:0>			U1IS<1:0>		0000
1100	IPC7	31:16	—	—	—	SPI2IP<2:0>			SPI2IS<1:0>		—	—	—	CMP2IP<2:0>			CMP2IS<1:0>		0000
		15:0	—	—	—	CMP1IP<2:0>			CMP1IS<1:0>		—	—	—	PMPIP<2:0>			PMPIS<1:0>		0000
1110	IPC8	31:16	—	—	—	RTCCIP<2:0>			RTCCIS<1:0>		—	—	—	FSCMIP<2:0>			FSCMIS<1:0>		0000
		15:0	—	—	—	I2C2IP<2:0>			I2C2IS<1:0>		—	—	—	U2IP<2:0>			U2IS<1:0>		0000
1120	IPC9	31:16	—	—	—	DMA3IP<2:0>			DMA3IS<1:0>		—	—	—	DMA2IP<2:0>			DMA2IS<1:0>		0000
		15:0	—	—	—	DMA1IP<2:0>			DMA1IS<1:0>		—	—	—	DMA0IP<2:0>			DMA0IS<1:0>		0000
1140	IPC11	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	USBIP<2:0>			USBIS<1:0>		—	—	—	FCEIP<2:0>			FCEIS<1:0>		0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: Except where noted, all registers in this table have corresponding CLR, SET, and INV registers at their virtual addresses, plus offsets of 0x4, 0x8, and 0xC, respectively. See **Section 12.1.1 "CLR, SET and INV Registers"** for more information.

2: This register does not have associated CLR, SET, and INV registers.

TABLE 4-43: USB REGISTERS MAP(1) (CONTINUED)

Virtual Address (BF88_#)	Register Name	Bit Range	Bits															All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
5380	U1EP8	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	EPCONDIS	EPRXEN	EPTXEN	EPSTALL	EPHSHK	0000
5390	U1EP9	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	EPCONDIS	EPRXEN	EPTXEN	EPSTALL	EPHSHK	0000
53A0	U1EP10	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	EPCONDIS	EPRXEN	EPTXEN	EPSTALL	EPHSHK	0000
53B0	U1EP11	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	EPCONDIS	EPRXEN	EPTXEN	EPSTALL	EPHSHK	0000
53C0	U1EP12	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	EPCONDIS	EPRXEN	EPTXEN	EPSTALL	EPHSHK	0000
53D0	U1EP13	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	EPCONDIS	EPRXEN	EPTXEN	EPSTALL	EPHSHK	0000
53E0	U1EP14	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	EPCONDIS	EPRXEN	EPTXEN	EPSTALL	EPHSHK	0000
53F0	U1EP15	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	EPCONDIS	EPRXEN	EPTXEN	EPSTALL	EPHSHK	0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: Except where noted, all registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 12.1.1 "CLR, SET and INV Registers"** for more information.

2: This register does not have associated CLR, SET, and INV registers.

3: All bits in this register are read-only; therefore, CLR, SET, and INV registers are not supported.

4: The reset value for this bit is undefined.

5.0 FLASH PROGRAM MEMORY

Note 1: This data sheet summarizes the features of the PIC32MX3XX/4XX family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 5. "Flash Program Memory"** (DS61121) of the *"PIC32 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com/PIC32).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

PIC32MX3XX/4XX devices contain an internal program Flash memory for executing user code. There are three methods by which the user can program this memory:

- Run-Time Self Programming (RTSP)
- In-Circuit Serial Programming™ (ICSP™)
- EJTAG Programming

RTSP is performed by software executing from either Flash or RAM memory. EJTAG is performed using the EJTAG port of the device and a EJTAG capable programmer. ICSP is performed using a serial data connection to the device and allows much faster programming times than RTSP. RTSP techniques are described in this chapter. The ICSP and EJTAG methods are described in the "*PIC32MX Flash Programming Specification*" (DS61145), which can be downloaded from the Microchip web site.

Note: Flash LVD Delay (LVDstartup) must be taken into account between setting up and executing any Flash command operation. See Example 5-1 for a code example to set up and execute a Flash command operation.

EXAMPLE 5-1:

```
NVMCON = 0x4004;          // Enable and configure for erase operation
Wait(delay);              // Delay for 6 µs for LVDstartup

NVMKEY = 0xAA996655;
NVMKEY = 0x556699AA;
NVMCONSET = 0x8000;       // Initiate operation

while(NVMCONbits.WR==1);  // Wait for current operation to complete
```

NOTES:

17.0 SERIAL PERIPHERAL INTERFACE (SPI)

Note 1: This data sheet summarizes the features of the PIC32MX3XX/4XX family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 23. "Serial Peripheral Interface (SPI)"** (DS61106) of the *"PIC32 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com/PIC32).

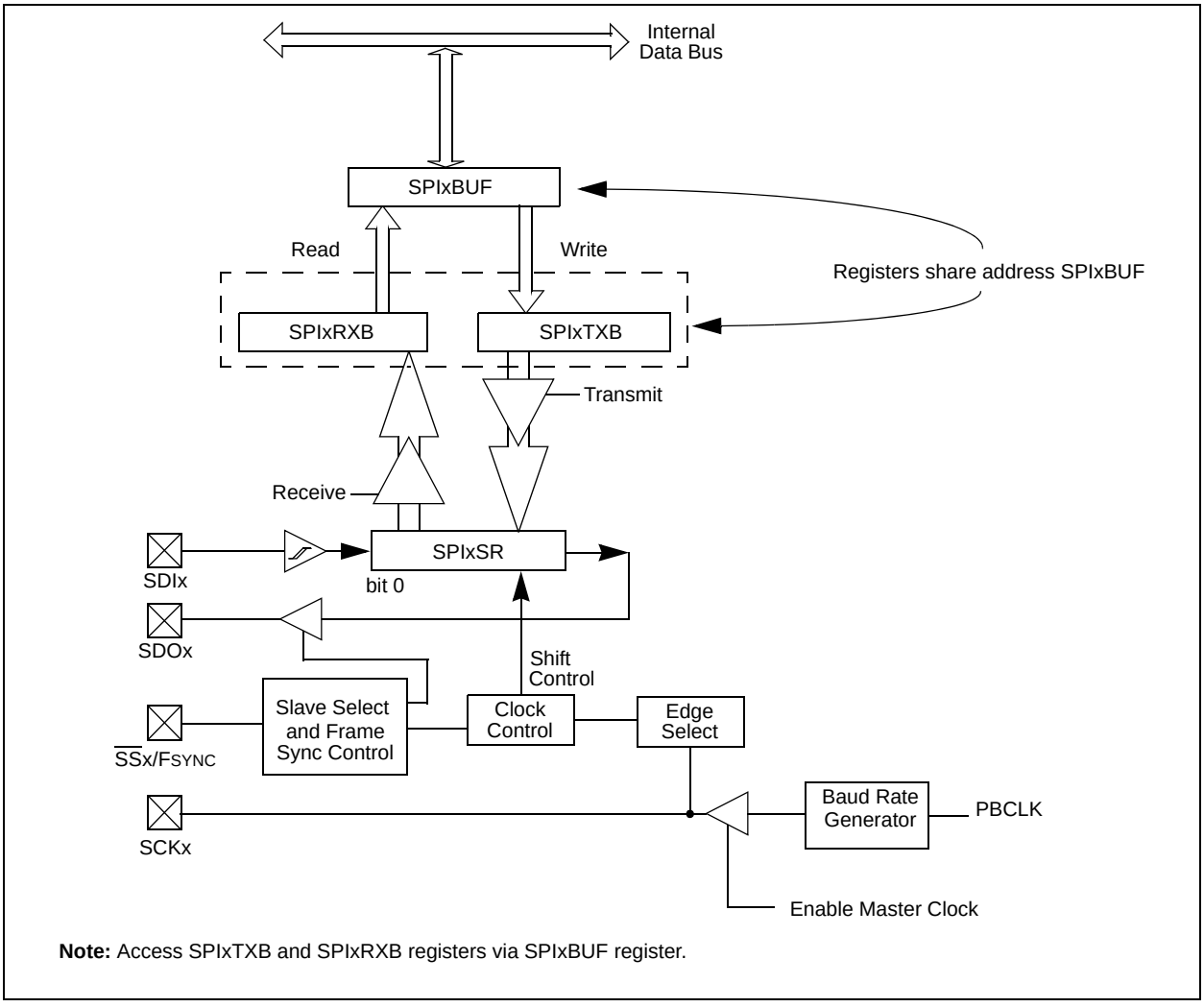
2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The SPI module is a synchronous serial interface useful for communicating with external peripherals and other microcontroller devices. These peripheral devices may be Serial EEPROMs, shift registers, display drivers, Analog-to-Digital Converters, etc. The PIC32MX SPI module is compatible with Motorola® SPI and SIOP interfaces.

Following are some of the key features of this module:

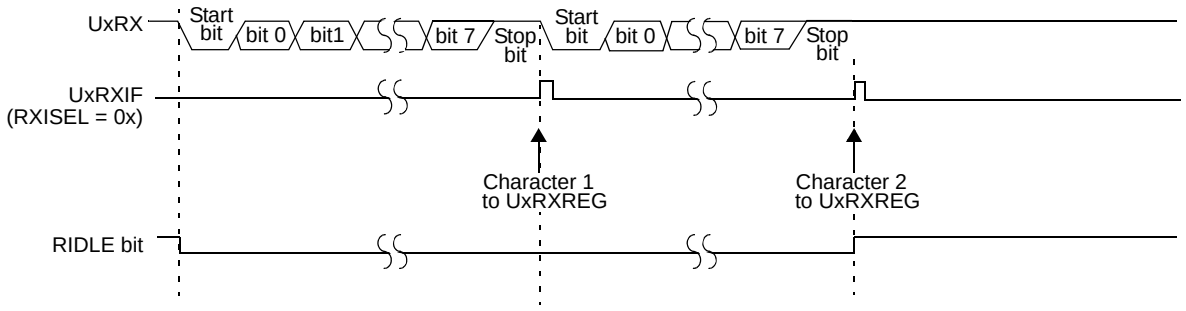
- Master and Slave Modes Support
- Four Different Clock Formats
- Framed SPI Protocol Support
- User Configurable 8-bit, 16-bit and 32-bit Data Width
- Separate SPI Data Registers for Receive and Transmit
- Programmable Interrupt Event on every 8-bit, 16-bit and 32-bit Data Transfer
- Operation during CPU Sleep and Idle Mode
- Fast Bit Manipulation using CLR, SET and INV Registers

FIGURE 17-1: SPI MODULE BLOCK DIAGRAM



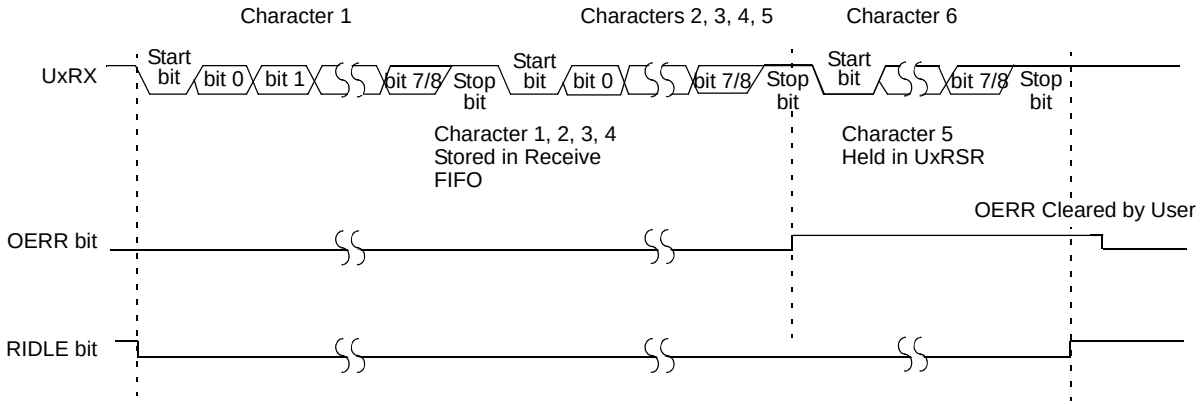
Note: Access SPIxTXB and SPIxRXB registers via SPIxBUF register.

FIGURE 19-4: UART RECEPTION



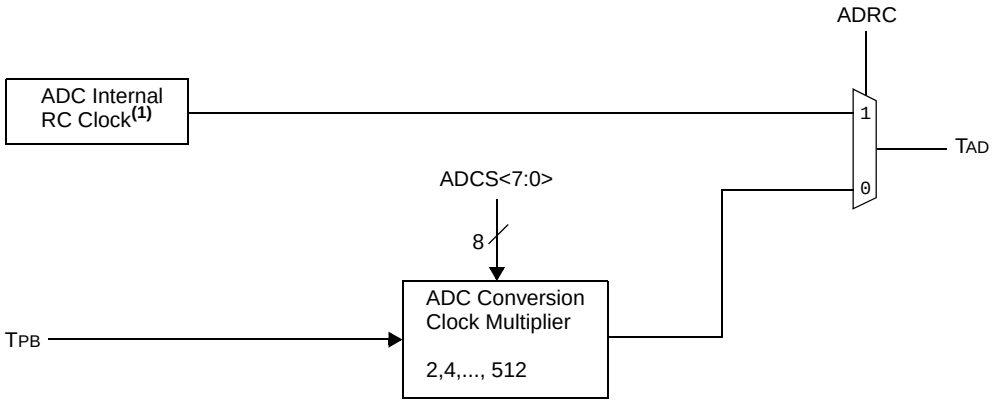
Note: This timing diagram shows 2 characters received on the UxRX input.

FIGURE 19-5: UART RECEPTION WITH RECEIVE OVERRUN



Note: This diagram shows 6 characters received without the user reading the input buffer. The 5th character received is held in the Receive Shift register. An overrun error occurs at the start of the 6th character.

FIGURE 22-2: ADC CONVERSION CLOCK PERIOD BLOCK DIAGRAM



Note 1: See the ADC electrical characteristics for the exact RC clock value.

26.3 On-Chip Voltage Regulator

All PIC32MX3XX/4XX device's core and digital logic are designed to operate at a nominal 1.8V. To simplify system designs, most devices in the PIC32MX3XX/4XX incorporate an on-chip regulator providing the required core logic voltage from VDD.

The internal 1.8V regulator is controlled by the ENVREG pin. Tying this pin to VDD enables the regulator, which in turn provides power to the core. A low ESR capacitor (such as tantalum) must be connected to the VCORE/VCAP pin (Figure 26-2). This helps to maintain the stability of the regulator. The recommended value for the filer capacitor is provided in **Section 29.1 "DC Characteristics"**.

Note:	It is important that the low ESR capacitor is placed as close as possible to the VCORE/VCAP pin.

Tying the ENVREG pin to VSS disables the regulator. In this case, separate power for the core logic at a nominal 1.8V must be supplied to the device on the VCORE/VCAP pin.

Alternatively, the VCORE/VCAP and VDD pins can be tied together to operate at a lower nominal voltage. Refer to Figure 26-2 for possible configurations.

26.3.1 ON-CHIP REGULATOR AND POR

When the voltage regulator is enabled, it takes fixed delay for it to generate output. During this time, designated as TPU, code execution is disabled. TPU is applied every time the device resumes operation after any power-down, including Sleep mode.

If the regulator is disabled, a separate Power-up Timer (PWRT) is automatically enabled. The PWRT adds a fixed delay of TPWRT at device start-up. See **Section 29.0 "Electrical Characteristics"** for more information on TPU AND TPWRT.

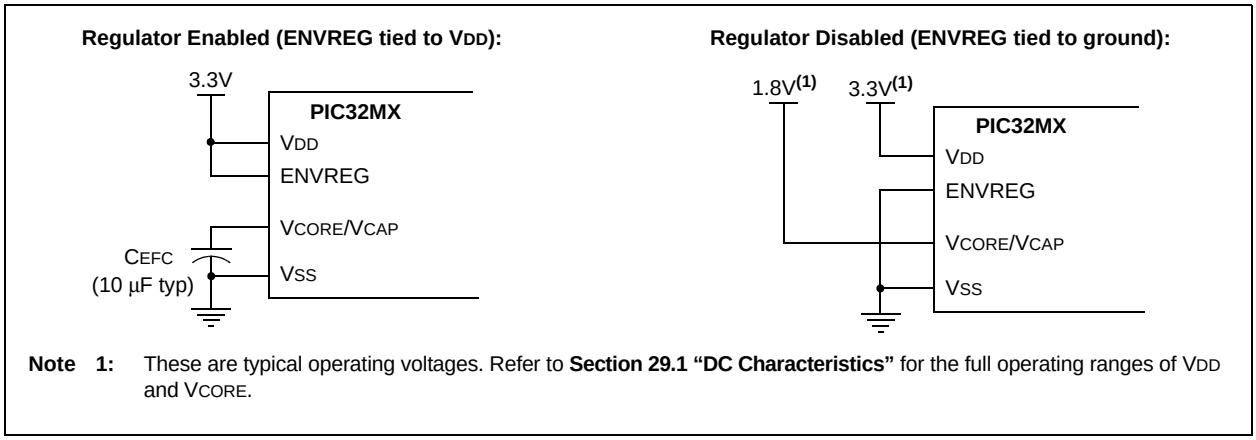
26.3.2 ON-CHIP REGULATOR AND BOR

When the on-chip regulator is enabled, PIC32MX3XX/4XX devices also have a simple brown-out capability. If the voltage supplied to the regulator is inadequate to maintain a regulated level, the regulator Reset circuitry will generate a Brown-out Reset. This event is captured by the BOR flag bit (RCON<1>). The brown-out voltage levels are specific in **Section 29.1 "DC Characteristics"**.

26.3.3 POWER-UP REQUIREMENTS

The on-chip regulator is designed to meet the power-up requirements for the device. If the application does not use the regulator, then strict power-up conditions must be adhered to. While powering up, VCORE must never exceed VDD by 0.3 volts.

FIGURE 26-2: CONNECTIONS FOR THE ON-CHIP REGULATOR



Note 1: These are typical operating voltages. Refer to **Section 29.1 "DC Characteristics"** for the full operating ranges of VDD and VCORE.

TABLE 27-1: MIPS32® INSTRUCTION SET (CONTINUED)

Instruction	Description	Function

BLEZL	Branch on Less Than or Equal to Zero Likely(1)	if Rs[31] || Rs == 0
		  PC += (int)offset
		else
		  Ignore Next Instruction

BLTZ	Branch on Less Than Zero	if Rs[31] PC += (int)offset
BLTZAL	Branch on Less Than Zero and Link	GPR[31] = PC + 8 if Rs[31] PC += (int)offset

BLTZALL	Branch on Less Than Zero and Link Likely(1)	GPR[31] = PC + 8
		if Rs[31]
		  PC += (int)offset
		else
		  Ignore Next Instruction

BLTZL	Branch on Less Than Zero Likely(1)	if Rs[31]
		  PC += (int)offset
		else
		  Ignore Next Instruction

BNE	Branch on Not Equal	if Rs != Rt PC += (int)offset

BNEL	Branch on Not Equal Likely(1)	if Rs != Rt
		  PC += (int)offset
		else
		  Ignore Next Instruction

BREAK	Breakpoint	Break Exception
CLO	Count Leading Ones	Rd = NumLeadingOnes(Rs)
CLZ	Count Leading Zeroes	Rd = NumLeadingZeroes(Rs)
DERET	Return from Debug Exception	PC = DEPC Exit Debug Mode
DI	Atomically Disable Interrupts	Rt = Status; $Status_{IE}$ = 0
DIV	Divide	LO = (int)Rs / (int)Rt HI = (int)Rs % (int)Rt
DIVU	Unsigned Divide	LO = (uns)Rs / (uns)Rt HI = (uns)Rs % (uns)Rt
EHB	Execution Hazard Barrier	Stop instruction execution until execution hazards are cleared
EI	Atomically Enable Interrupts	Rt = Status; $Status_{IE}$ = 1

ERET	Return from Exception	if $Status_{ERL}$
		  PC = ErrorEPC
		else
		  PC = EPC
		  $Status_{EXL}$ = 0
		$Status_{ERL}$ = 0
		LL = 0

EXT	Extract Bit Field	Rt = ExtractField(Rs, pos, size)
INS	Insert Bit Field	Rt = InsertField(Rs, Rt, pos, size)
J	Unconditional Jump	PC = PC[31:28] || offset<<2

Note 1: This instruction is deprecated and should not be used.

TABLE 27-1: MIPS32® INSTRUCTION SET (CONTINUED)

Instruction	Description	Function
JAL	Jump and Link	GPR[31] = PC + 8 PC = PC[31:28] || offset<<2
JALR	Jump and Link Register	Rd = PC + 8 PC = Rs
JALR.HB	Jump and Link Register with Hazard Barrier	Like JALR, but also clears execution and instruction hazards
JR	Jump Register	PC = Rs
JR.HB	Jump Register with Hazard Barrier	Like JR, but also clears execution and instruction hazards
LB	Load Byte	Rt = (byte)Mem[Rs+offset]
LBU	Unsigned Load Byte	Rt = (ubyte))Mem[Rs+offset]
LH	Load Halfword	Rt = (half)Mem[Rs+offset]
LHU	Unsigned Load Halfword	Rt = (uhalf)Mem[Rs+offset]
LL	Load Linked Word	Rt = Mem[Rs+offset> LL_{bit} = 1 LLAdr = Rs + offset
LUI	Load Upper Immediate	Rt = immediate << 16
LW	Load Word	Rt = Mem[Rs+offset]
LWPC	Load Word, PC relative	Rt = Mem[PC+offset]
LWL	Load Word Left	Re = Re MERGE Mem[Rs+offset]
LWR	Load Word Right	Re = Re MERGE Mem[Rs+offset]
MADD	Multiply-Add	HI | LO += (int)Rs * (int)Rt
MADDU	Multiply-Add Unsigned	HI | LO += (uns)Rs * (uns)Rt
MFC0	Move from Coprocessor 0	Rt = CPR[0, Rd, sel]
MFHI	Move from HI	Rd = HI
MFLO	Move from LO	Rd = LO
MOVN	Move Conditional on Not Zero	if Rt ¼ 0 then Rd = Rs
MOVZ	Move Conditional on Zero	if Rt = 0 then Rd = Rs
MSUB	Multiply-Subtract	HI | LO -= (int)Rs * (int)Rt
MSUBU	Multiply-Subtract Unsigned	HI | LO -= (uns)Rs * (uns)Rt
MTC0	Move to Coprocessor 0	CPR[0, n, Sel] = Rt
MTHI	Move to HI	HI = Rs
MTLO	Move to LO	LO = Rs
MUL	Multiply with register write	HI | LO =Unpredictable Rd = ((int)Rs * (int)$Rt)_{31..0}$
MULT	Integer Multiply	HI | LO = (int)Rs * (int)Rd
MULTU	Unsigned Multiply	HI | LO = (uns)Rs * (uns)Rd
NOP	No Operation (Assembler idiom for: SLL r0, r0, r0)	
NOR	Logical NOR	Rd = ~(Rs | Rt)
OR	Logical OR	Rd = Rs | Rt
ORI	Logical OR Immediate	Rt = Rs | Immed
RDHWR	Read Hardware Register (if enabled by $HWRE_{na}$ Register)	Re = HWR[Rd]

Note 1: This instruction is deprecated and should not be used.

28.0 DEVELOPMENT SUPPORT

The PIC® microcontrollers and dsPIC® digital signal controllers are supported with a full range of software and hardware development tools:

- Integrated Development Environment
  - MPLAB® IDE Software
- Compilers/Assemblers/Linkers
  - MPLAB C Compiler for Various Device Families
  - HI-TECH C for Various Device Families
  - MPASM™ Assembler
  - MPLINK™ Object Linker/ MPLIB™ Object Librarian
  - MPLAB Assembler/Linker/Librarian for Various Device Families
- Simulators
  - MPLAB SIM Software Simulator
- Emulators
  - MPLAB REAL ICE™ In-Circuit Emulator
- In-Circuit Debuggers
  - MPLAB ICD 3
  - PICkit™ 3 Debug Express
- Device Programmers
  - PICkit™ 2 Programmer
  - MPLAB PM3 Device Programmer
- Low-Cost Demonstration/Development Boards, Evaluation Kits, and Starter Kits

28.1 MPLAB Integrated Development Environment Software

The MPLAB IDE software brings an ease of software development previously unseen in the 8/16/32-bit microcontroller market. The MPLAB IDE is a Windows® operating system-based application that contains:

- A single graphical interface to all debugging tools
  - Simulator
  - Programmer (sold separately)
  - In-Circuit Emulator (sold separately)
  - In-Circuit Debugger (sold separately)
- A full-featured editor with color-coded context
- A multiple project manager
- Customizable data windows with direct edit of contents
- High-level source code debugging
- Mouse over variable inspection
- Drag and drop variables from source to watch windows
- Extensive on-line help
- Integration of select third party tools, such as IAR C Compilers

The MPLAB IDE allows you to:

- Edit your source files (either C or assembly)
- One-touch compile or assemble, and download to emulator and simulator tools (automatically updates all project information)
- Debug using:
  - Source files (C or assembly)
  - Mixed C and assembly
  - Machine code

MPLAB IDE supports multiple debugging tools in a single development paradigm, from the cost-effective simulators, through low-cost in-circuit debuggers, to full-featured emulators. This eliminates the learning curve when upgrading to tools with increased flexibility and power.

29.0 ELECTRICAL CHARACTERISTICS

This section provides an overview of PIC32MX3XX/4XX electrical characteristics. Additional information will be provided in future revisions of this document as it becomes available.

Absolute maximum ratings for the PIC32MX3XX/4XX are listed below. Exposure to these maximum rating conditions for extended periods may affect device reliability. Functional operation of the device at these or any other conditions above the parameters indicated in the operation listings of this specification is not implied.

Absolute Maximum Ratings (Note 1)

Ambient temperature under bias ..... -40°C to +105°C
Storage temperature ..... -65°C to +150°C
Voltage on V_{DD} with respect to V_{SS} ..... -0.3V to +4.0V
Voltage on any pin that is not 5V tolerant, with respect to V_{SS} **(Note 3)** ..... -0.3V to (V_{DD} + 0.3V)
Voltage on any 5V tolerant pin with respect to V_{SS} when $V_{DD} \geq 2.3V$ **(Note 3)** ..... -0.3V to +5.5V
Voltage on any 5V tolerant pin with respect to V_{SS} when $V_{DD} < 2.3V$ **(Note 3)** ..... -0.3V to +3.6V
Voltage on V_{CORE} with respect to V_{SS} ..... -0.3V to 2.0V
Voltage on V_{BUS} with respect to V_{SS} ..... -0.3V to +5.5V
Maximum current out of V_{SS} pin(s) ..... 300 mA
Maximum current into V_{DD} pin(s) **(Note 2)** ..... 300 mA
Maximum output current sunk by any I/O pin ..... 25 mA
Maximum output current sourced by any I/O pin ..... 25 mA
Maximum current sunk by all ports ..... 200 mA
Maximum current sourced by all ports **(Note 2)** ..... 200 mA

Note 1: Stresses above those listed under **"Absolute Maximum Ratings"** may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

2: Maximum allowable current is a function of device maximum power dissipation (see Table 29-2).

3: See the **"Pin Diagrams"** section for the 5V tolerant pins.

TABLE 29-13: COMPARATOR SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+105°C for V-Temp				
Param. No.	**Symbol**	**Characteristics**	**Min.**	**Typical**	**Max.**	**Units**	**Comments**
D300	VIOFF	Input Offset Voltage	—	±7.5	±25	mV	AVDD = VDD, AVSS = VSS
D301	VICM	Input Common Mode Voltage	0	—	VDD	V	AVDD = VDD, AVSS = VSS **(Note 2)**
D302	CMRR	Common Mode Rejection Ratio	55	—	—	dB	Max VICM = (VDD - 1)V **(Note 2)**
D303	TRESP	Response Time	—	150	400	ns	AVDD = VDD, AVSS = VSS **(Notes 1,2)**
D304	ON2OV	Comparator Enabled to Output Valid	—	—	10	µs	Comparator module is configured before setting the comparator ON bit. **(Note 2)**
D305	IVREF	Internal Voltage Reference	0.57	0.6	0.63	V	—

Note 1: Response time measured with one comparator input at (VDD – 1.5)/2, while the other input transitions from VSS to VDD.

2: These parameters are characterized but not tested.

TABLE 29-14: VOLTAGE REFERENCE SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+105°C for V-Temp				
Param. No.	**Symbol**	**Characteristics**	**Min.**	**Typical**	**Max.**	**Units**	**Comments**
D310	VRES	Resolution	VDD/24	—	VDD/32	LSb	—
D311	VRAA	Absolute Accuracy	—	—	1/2	LSb	—
D312	TSET	Settling Time(1)	—	—	10	µs	—

Note 1: Settling time measured while CVRR = 1 and CVR3:CVR0 transitions from '0000' to '1111'. This parameter is characterized, but not tested in manufacturing.

TABLE 29-15: INTERNAL VOLTAGE REGULATOR SPECIFICATIONS

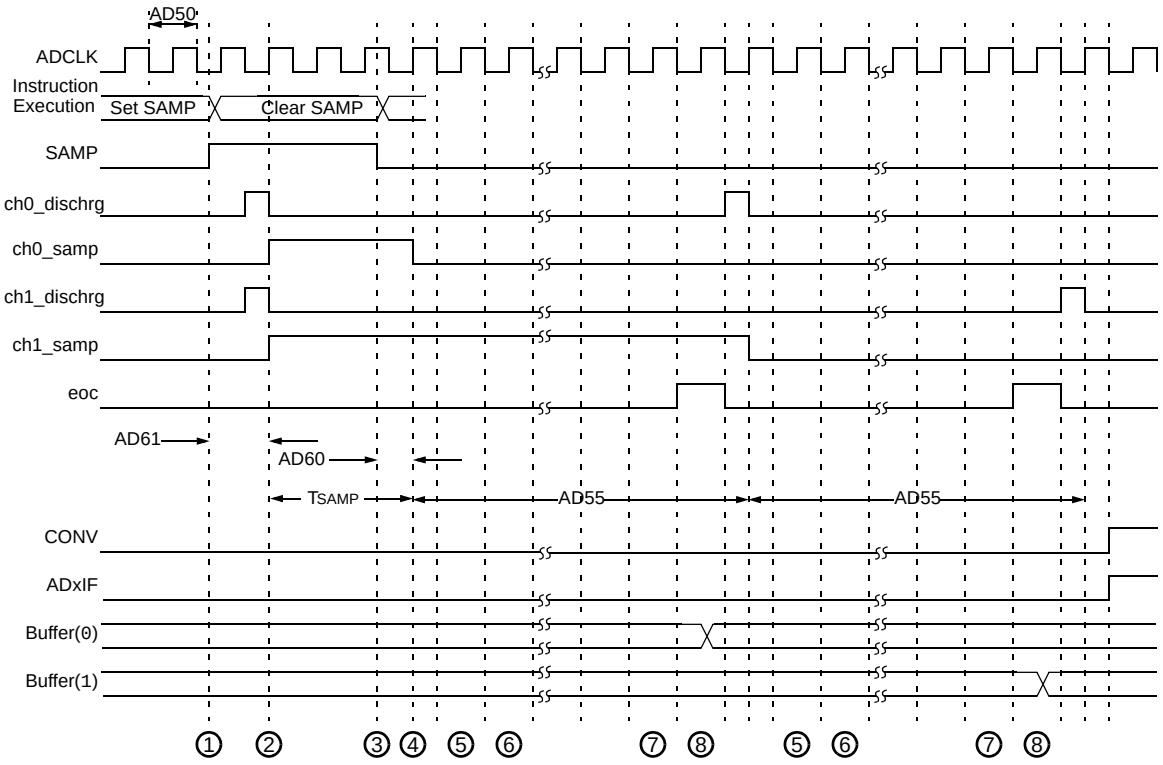
DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+105°C for V-Temp				
Param. No.	**Symbol**	**Characteristics**	**Min.**	**Typical**	**Max.**	**Units**	**Comments**
D320	VCORE	Regulator Output Voltage	1.62	1.80	1.98	V	—
D321	CEFC	External Filter Capacitor Value	8	10	—	µF	Capacitor must be low series resistance (< 1 Ohm)
D322	TPWRT	Power-up Timer Period	—	64	—	ms	ENVREG = 0

TABLE 29-24: TIMER2, 3, 4, 5 EXTERNAL CLOCK TIMING REQUIREMENTS

AC CHARACTERISTICS				Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+105°C for V-Temp				
Param. No.	**Symbol**	**Characteristics(1)**		**Min.**	**Max.**	**Units**	**Conditions**	
TB10	TTXH	TxCK High Time	Synchronous, with prescaler	[(12.5 ns or 1TPB)/N] + 25 ns	—	ns	Must also meet parameter TB15.	N = prescale value (1, 2, 4, 8, 16, 32, 64, 256)
TB11	TTXL	TxCK Low Time	Synchronous, with prescaler	[(12.5 ns or 1TPB)/N] + 25 ns	—	ns	Must also meet parameter TB15.	
TB15	TTXP	TxCK Input Period	Synchronous, with prescaler	[(Greater of 25 ns or 2 TPB)/N] + 30 ns	—	ns	VDD > 2.7V	
				[(Greater of 25 ns or 2 TPB)/N] + 50 ns	—	ns	VDD < 2.7V	—
TB20	TCKEXTMRL	Delay from External TxCK Clock Edge to Timer Increment		—	1	TPB	—	

Note 1: These parameters are characterized, but not tested in manufacturing.

FIGURE 29-18: ANALOG-TO-DIGITAL CONVERSION (10-BIT MODE) TIMING CHARACTERISTICS (CHPS<1:0> = 01, SIMSAM = 0, ASAM = 0, SSRC<2:0> = 000)



(1) – Software sets ADxCON. SAMP to start sampling.

(2) – Sampling starts after discharge period. TSAMP is described in **Section 17. "10-bit Analog-to-Digital Converter (ADC)"** (DS61104) of the *"PIC32 Family Reference Manual"*.

(3) – Software clears ADxCON. SAMP to start conversion.

(4) – Sampling ends, conversion sequence starts.

(5) – Convert bit 9.

(6) – Convert bit 8.

(7) – Convert bit 0.

(8) – One TAD for end of conversion.

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